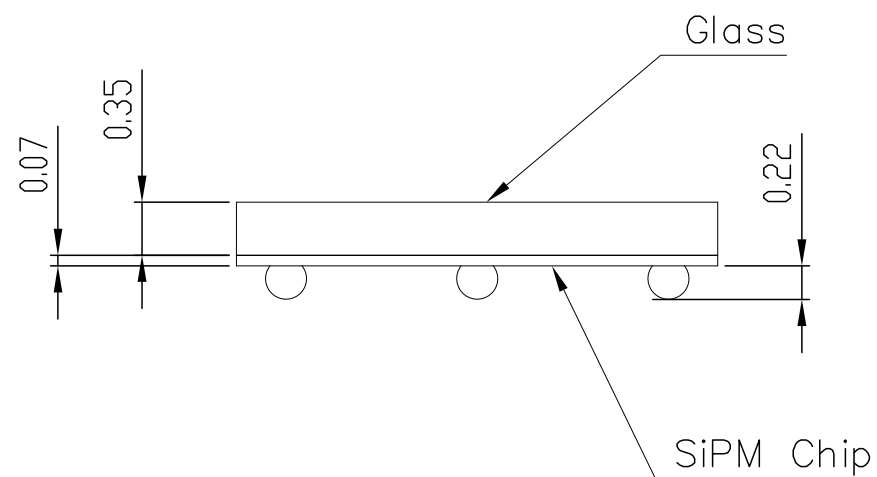
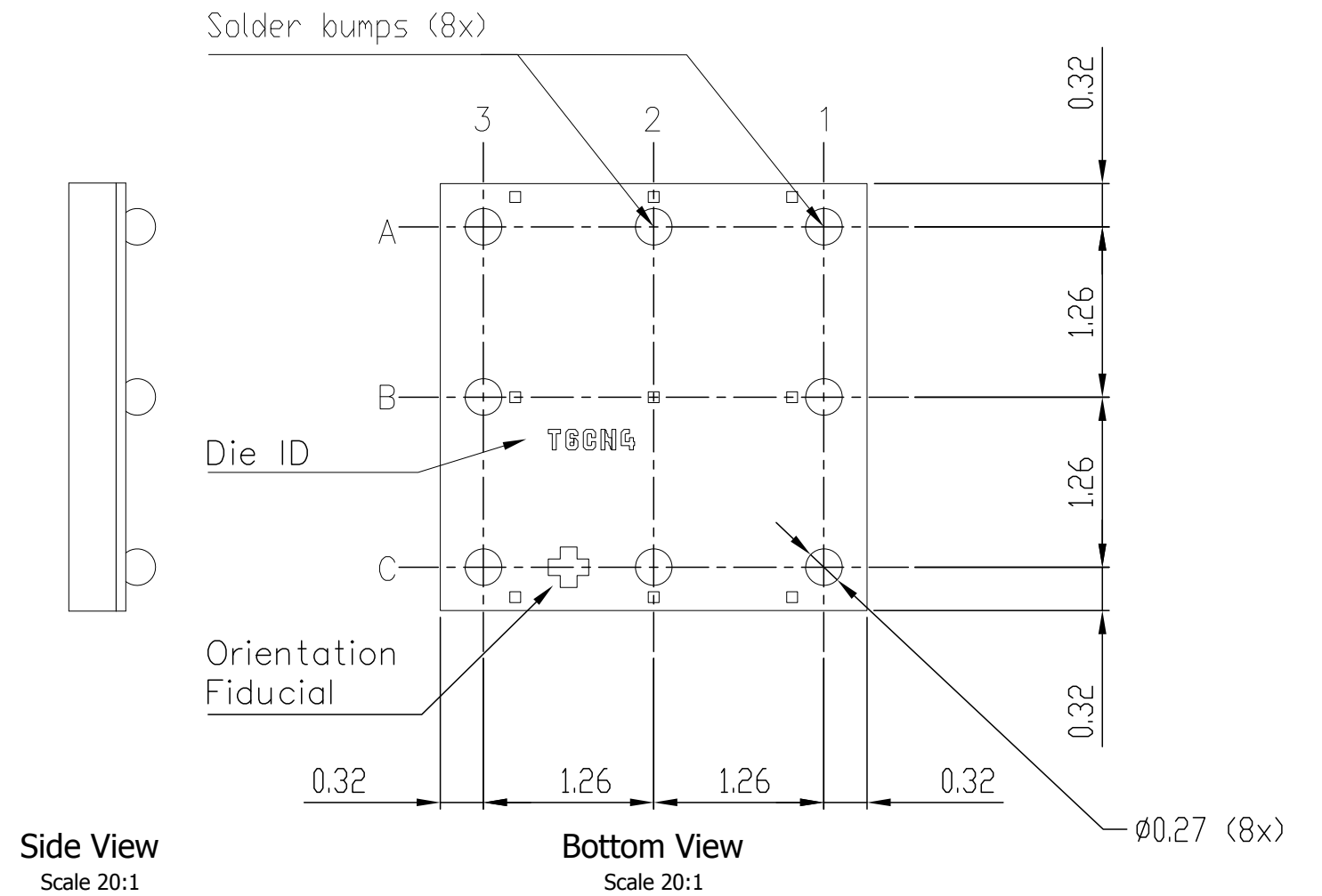


Top View
Scale 20:1

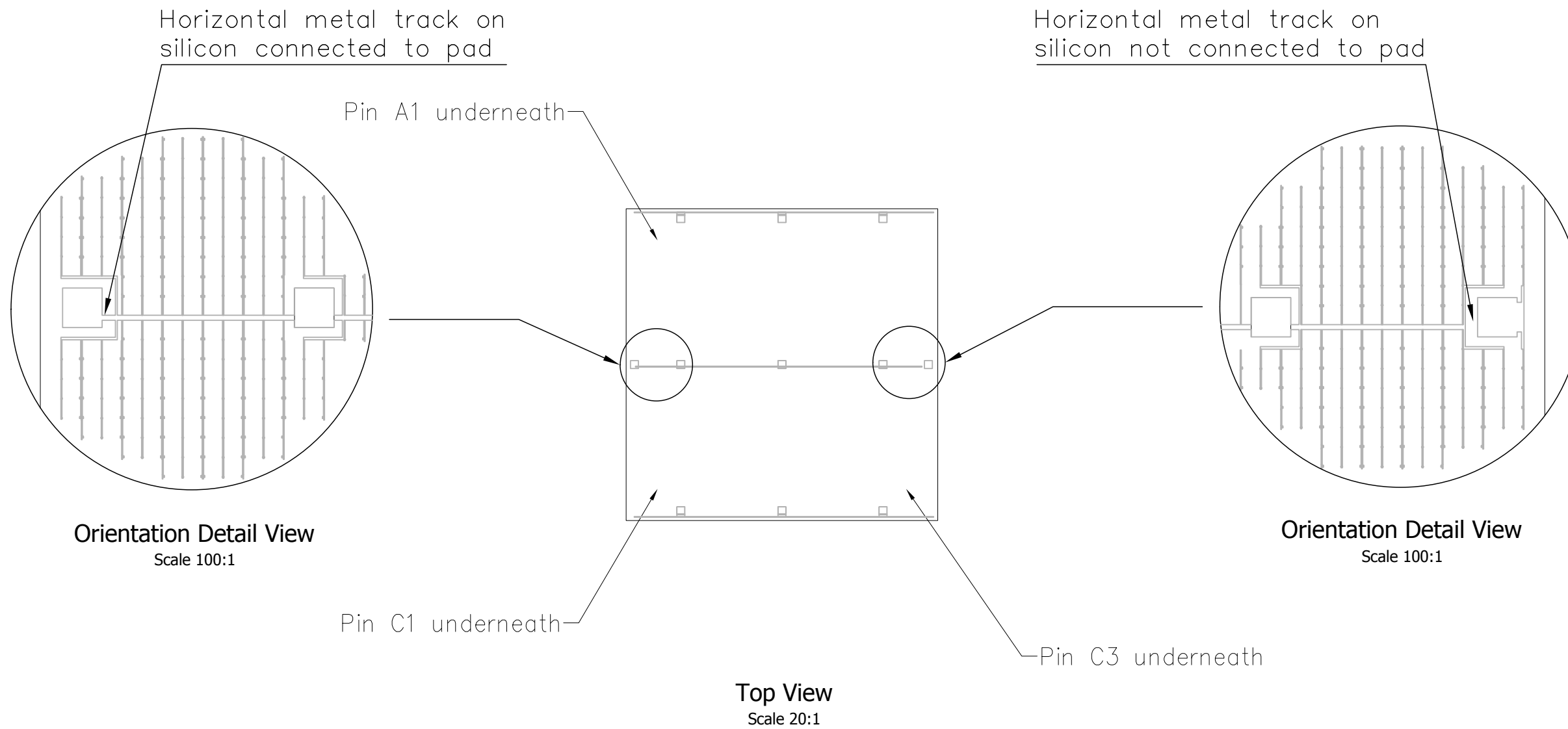


Side View
Scale 20:1

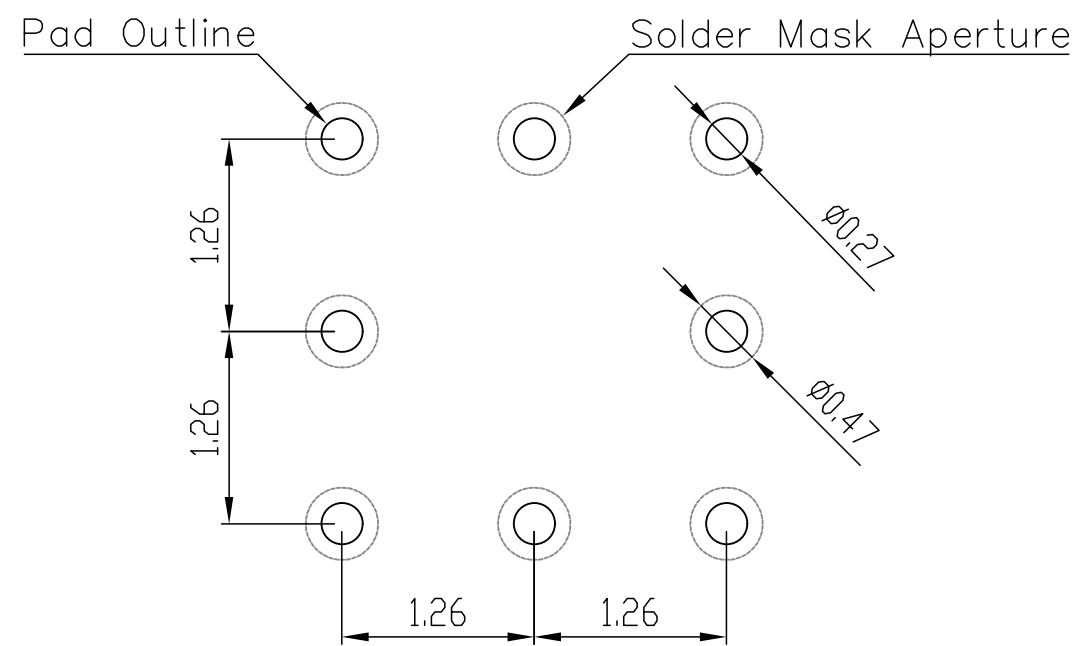
Pin Assignments

Pin #	Function
A1	Cathode
A2	NC
A3	NC
B1	Anode
B3	Fast Output
C1	NC
C2	NC
C3	Cathode

DATE	16 MAR 2016	REVISION	C	SCALE	20 : 1
SensL Technologies Ltd					Sheet
www.sensl.com					1 of 5
DWG. NO:	SND0161	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFJ-300xx-TSV-A1					
PROJECTION:					



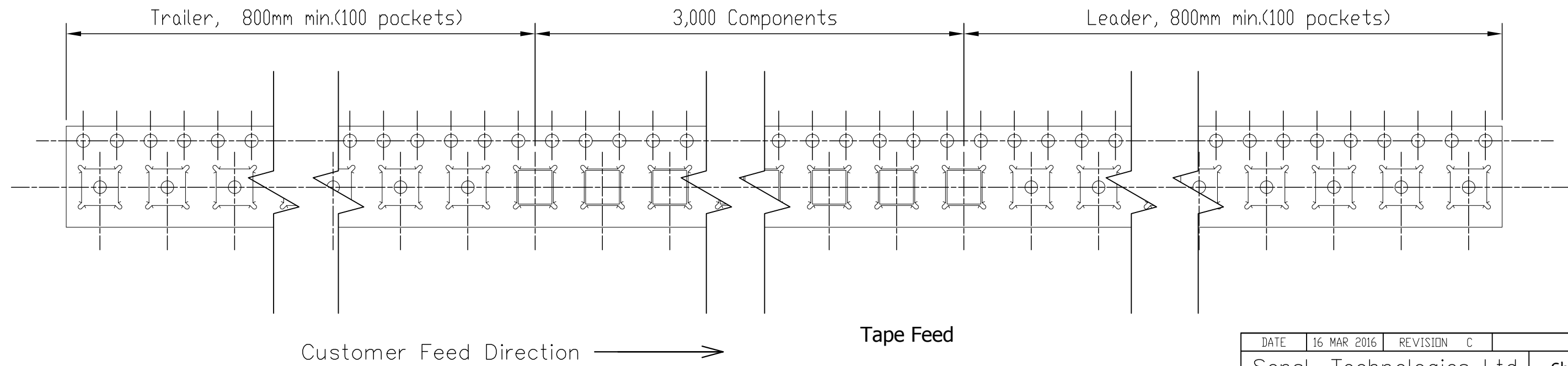
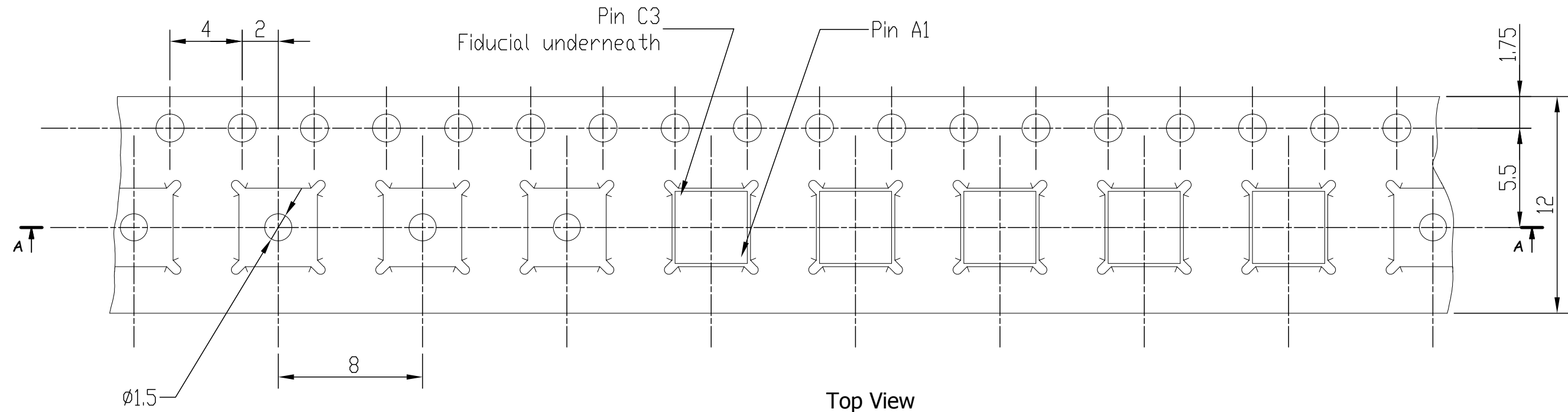
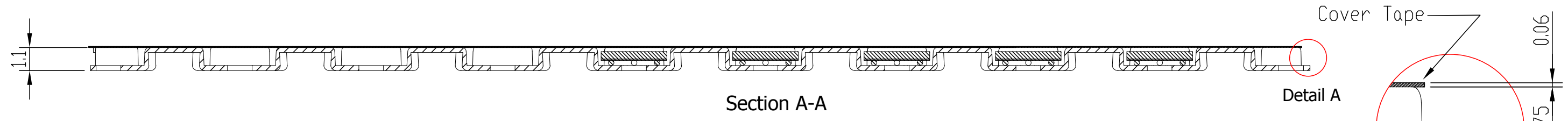
DATE	16 MAR 2016	REVISION	C	SCALE:	20 : 1
SensL Technologies Ltd www.sensl.com					Sheet 2 of 5
DWG. NO:	SND0161	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: MicroFJ-300xx-TSV-A1					
PROJECTION:					



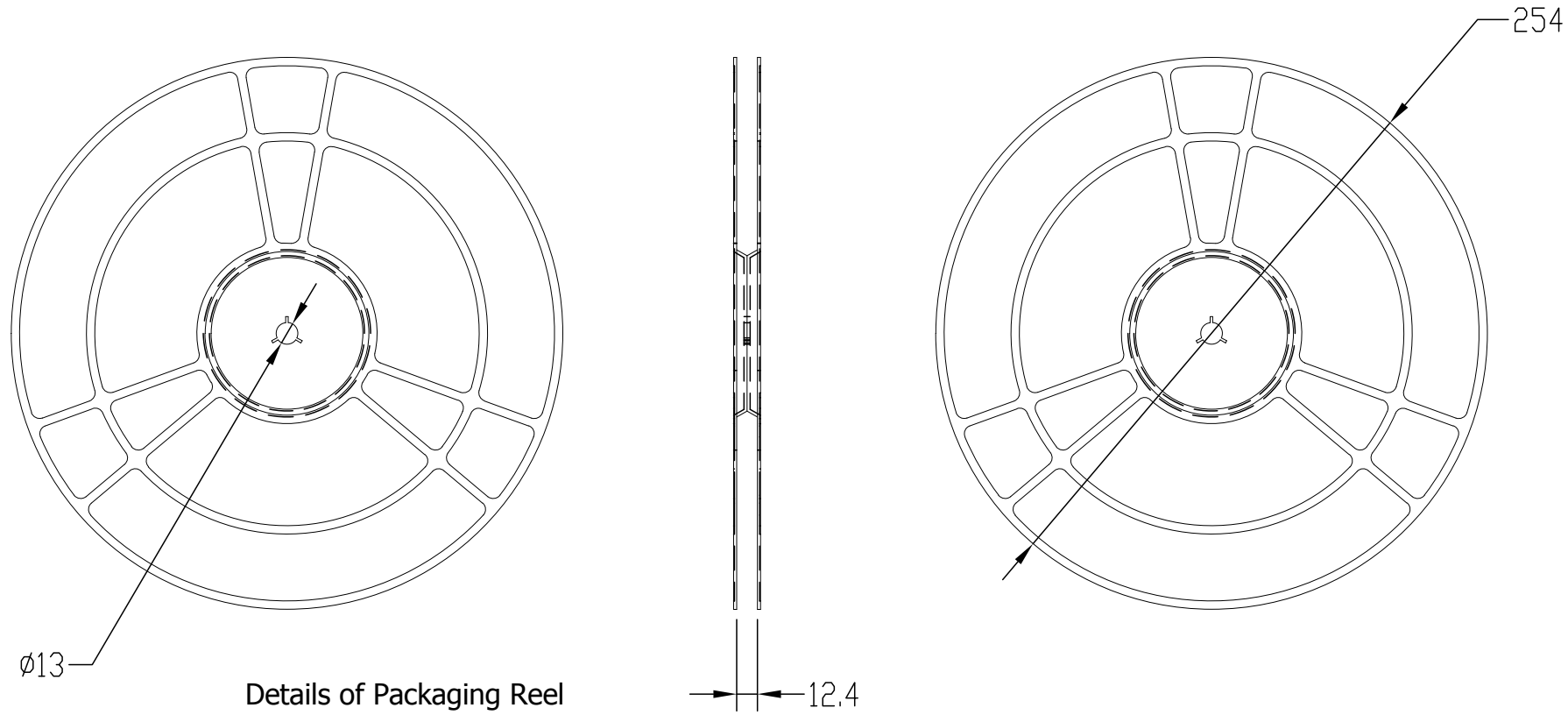
Recommended PCB Solder Footprint
Scale 20:1

NOTE: The No Connect (NC) pins are electrically isolated and should be soldered to a ground (or bias) plane to help with heat dissipation.

DATE	16 MAR 2016	REVISION	C	SCALE	20 : 1
SensL Technologies Ltd www.sensl.com					Sheet 3 of 5
DWG. NO:	SND0161	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: MicroFJ-300xx-TSV-A1					
PROJECTION:					



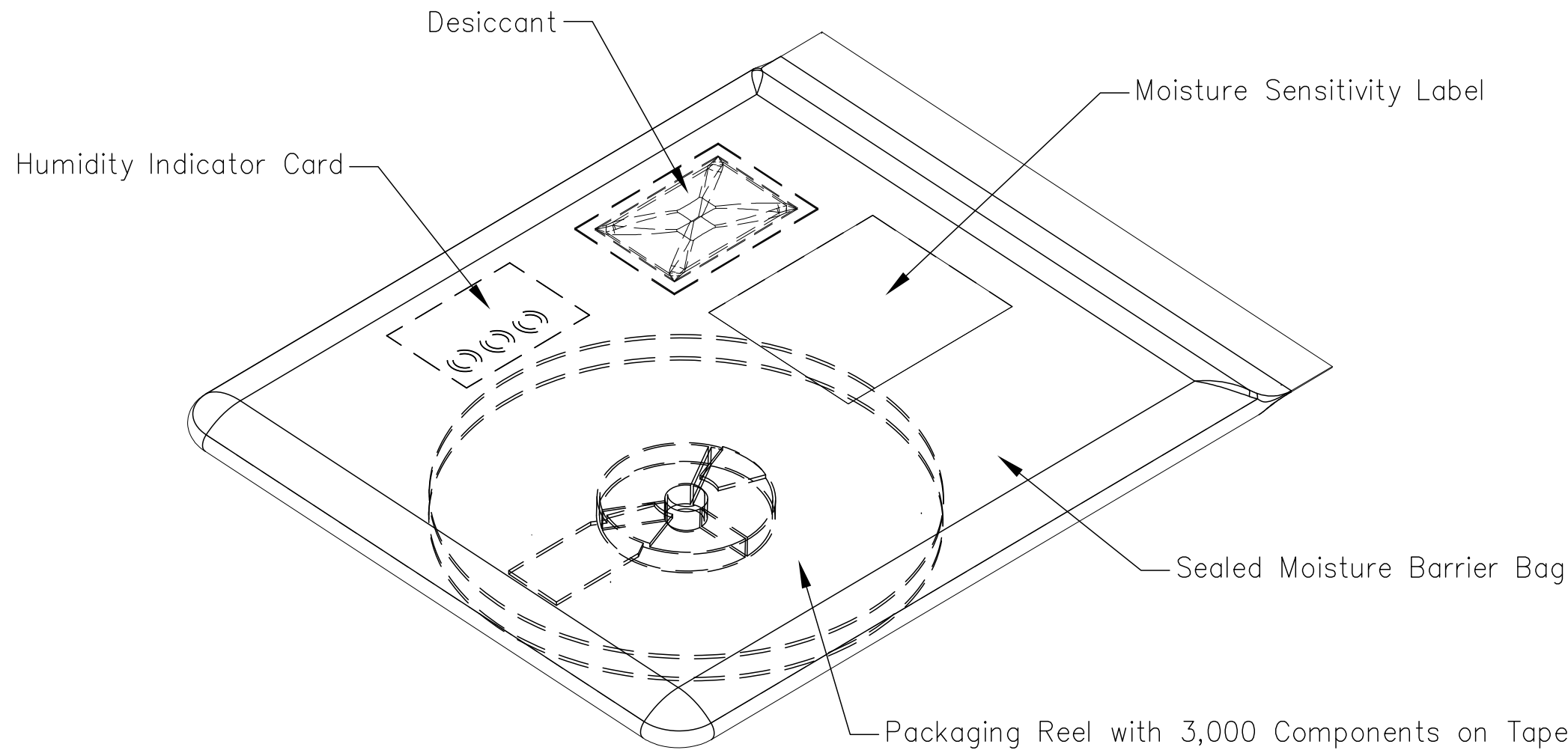
DATE	16 MAR 2016	REVISION	C
SensL Technologies Ltd			Sheet 4 of 5
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DWG. NO:	SND0161	DO NOT SCALE ALL DIMENSIONS IN MM	
TITLE:			
MicroFJ-300xx-TSV-A1			
PROJECTION:			



Details of Packaging Reel

	CAUTION	3
MOISTURE SENSITIVE DEVICES		
1. Calculated shelf life in sealed bag: 12 months at <math><40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C <small>If blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <u>168</u> hours of factory <small>If blank, see adjacent bar code label</small>		
conditions <math><30^{\circ}\text{C}</math>/60% RH, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: <u>20 Mar. 2014</u> <small>If blank, see adjacent bar code label</small>		
<small>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</small>		

Details of Moisture Sensitivity Label



5%	10%	60%
LEVEL 2A - 5A PARTS	LEVEL 2 PARTS	LEVEL 2 PARTS
Bake parts if 10% IS NOT BROWN and 5% IS AZURE	Bake parts if 60% IS NOT BROWN	Bake parts if 60% IS NOT BROWN
BROWN-DRY AZURE-WET		<small>Initial Use:</small>
COBALT FREE HUMIDITY INDICATOR		<small>DO NOT put this card into a bag if 60% dot is AZURE</small>
COMPLIES WITH IPC/JEDEC J-STD-033B		

Humidity Indicator Card

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DWG. NO:	SND0161	DO NOT SCALE	ALL DIMENSIONS IN MM
TITLE:			
MicroFJ-300xx-TSV-A1			
PROJECTION:			
		<small>2015 light</small>	